

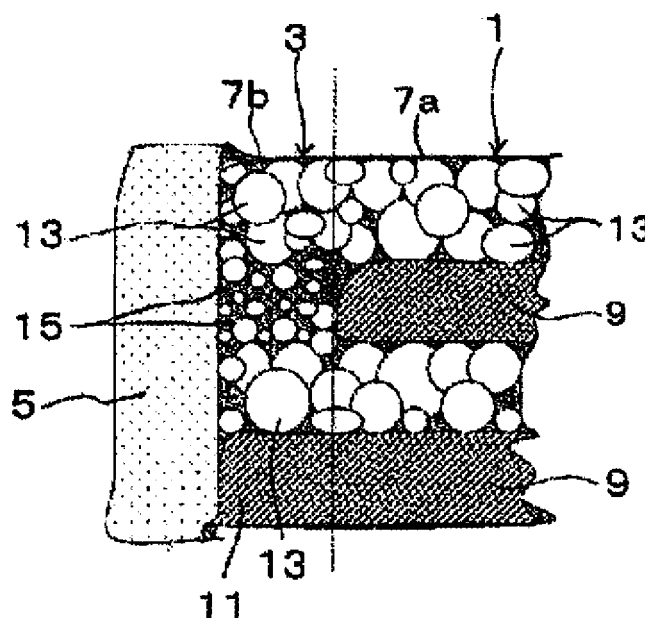
LAMINATED ELECTRONIC COMPONENT AND MANUFACTURING METHOD THEREFOR**Patent number:** JP2003017356**Publication date:** 2003-01-17**Inventor:** IWAIDA TOMOHIRO**Applicant:** KYOCERA CORP**Classification:****- international:** B32B7/02; H01G4/12; H01G4/30; B32B7/02;
H01G4/12; H01G4/30; (IPC1-7): H01G4/12; B32B7/02;
H01G4/30**- european:****Application number:** JP20010197119 20010628**Priority number(s):** JP20010197119 20010628

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Abstract of JP2003017356

PROBLEM TO BE SOLVED: To provide a laminated electronic component where a step due to the thickness of an inner electrode layer can be eliminated and the occurrence of a crack and delamination can be suppressed even if a dielectric ceramic layer is thinned and the number of laminations is increased, and to provide the manufacturing method.

SOLUTION: The inner electrode layer 9 and an inner electrode layer extending part 11 form the same plane which does not substantially have a step. The dielectric ceramic layer 7b of a non-capacity part 3 is constituted of a ceramic having sintering property higher than the dielectric ceramic layer 7a of a capacity part 1.



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